## Very Low Leakage Trench-based Schottky Rectifier

#### **Features**

- Fine Lithography Trench-based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- Low Thermal Resistance
- High Surge Capability
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Typical Applications**

- Switching Power Supplies including Notebook / Netbook Adapters, ATX and Flat Panel Display
- High Frequency and DC–DC Converters
- Freewheeling and OR-ing Diodes
- Reverse Battery Protection
- LED Lighting
- Instrumentation

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94–0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

1

• Device Meets MSL 1 Requirements

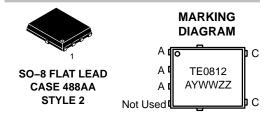


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# TRENCH SCHOTTKY RECTIFIERS 8 AMPERES 120 VOLTS





TE0812 = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

#### **ORDERING INFORMATION**

Device	Package	Shipping†
NRVTS8120EMFST1G	SO-8 FL (Pb-Free)	1500 / Tape & Reel
NRVTS8120EMFST3G	SO-8 FL (Pb-Free)	5000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	120	V
Average Rectified Forward Current (Rated $V_R$ , $T_C = 163^{\circ}C$ )	I <sub>F(AV)</sub>	8.0	А
Peak Repetitive Forward Current, (Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>C</sub> = 161°C)	I <sub>FRM</sub>	16	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	150	А
Storage Temperature Range	T <sub>stg</sub>	-65 to +175	°C
Operating Junction Temperature	TJ	-55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance, Junction–to–Lead, Steady State (Assumes 600 mm² 1 oz. copper bond pad, on a FR4 board)	$R_{\theta JC}$	-	2.7	°C/W

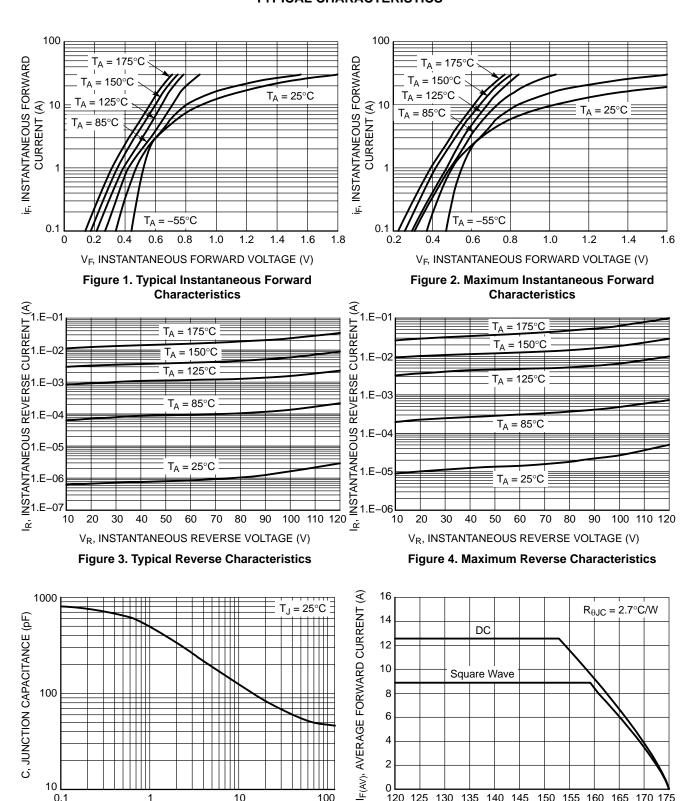
#### **ELECTRICAL CHARACTERISTICS**

Rating	Symbol	Тур	Max	Unit
Instantaneous Forward Voltage (Note 1)	V <sub>F</sub>			V
$(I_F = 4 \text{ A}, T_J = 25^{\circ}\text{C})$		0.648	_	
$(I_F = 8 \text{ A}, T_J = 25^{\circ}\text{C})$		0.826	0.88	
(I <sub>F</sub> = 4 A, T <sub>J</sub> = 125°C) (I <sub>F</sub> = 8 A, T <sub>J</sub> = 125°C)		0.542 0.613	- 0.65	
, , , , , , , , , , , , , , , , , , ,	1	0.013	0.03	
Instantaneous Reverse Current (Note 1) $(V_R = 90 \text{ V}, T_J = 25^{\circ}\text{C})$	I <sub>R</sub>	1.3	_	μΑ
(Rated dc Voltage, $T_J = 25^{\circ}\text{C}$ )		3.70	50	μΑ
$(V_R = 90 \text{ V}, T_J = 125^{\circ}\text{C})$		1.4	-	mA
(Rated dc Voltage, $T_J = 125^{\circ}C$ )		2.4	10	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width =  $300 \mu s$ , Duty Cycle  $\leq 2.0\%$ .

#### TYPICAL CHARACTERISTICS



V<sub>R</sub>, REVERSE VOLTAGE (V) Figure 5. Typical Junction Capacitance

0.1

10

T<sub>C</sub>, CASE TEMPERATURE (°C) Figure 6. Current Derating per Device

135 140 145 150 155 160 165 170 175

100

125

#### TYPICAL CHARACTERISTICS

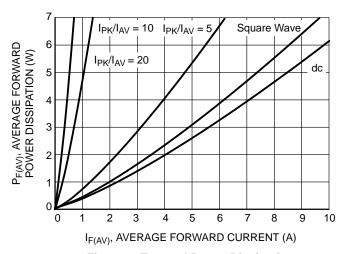


Figure 7. Forward Power Dissipation

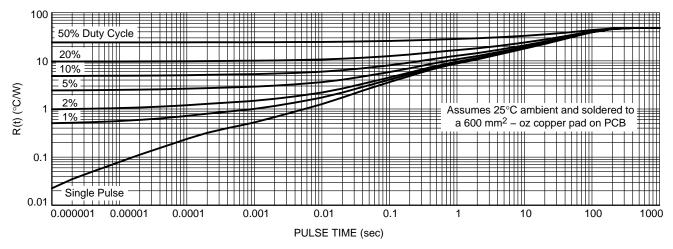


Figure 8. Typical Thermal Characteristics, Junction-to-Ambient

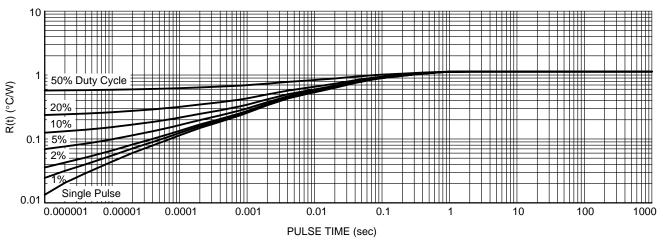
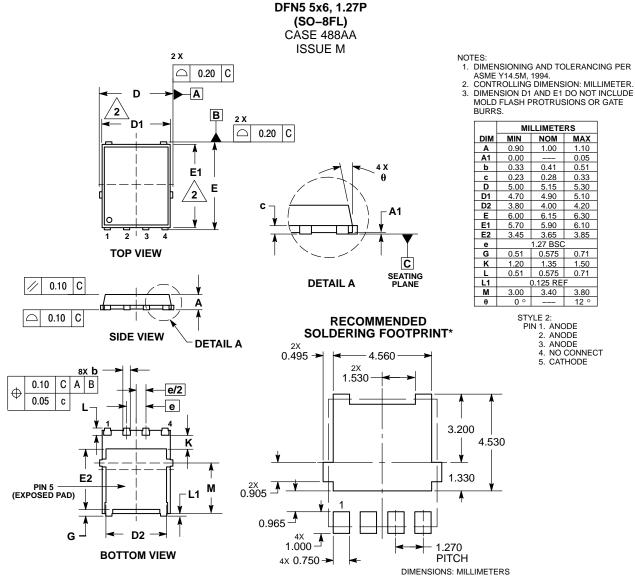


Figure 9. Typical Transient Thermal Response Characteristics, Junction-to-Case

#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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